



- 1. Chip material:Gap / GaP
- 2. Emitted color : Green
- 3. Lens Appearance : Green Diffused
- 4. Designed for ease in circuit board assembly.
- 5. Black case enhance contrast ratio.
- 6. Solid state light source.
- 7. Reliable and rugged.
- 8. 3mm diameter package.
- 9. This product don't contained restriction substance, compliance ROHS standard.

• Applications:

- 1. TV set
- 2. Monitor
- 3. Telephone
- 4. Computer
- 5. Circuit board

Absolute Maximum Ratings(Ta=25°C)

4.60	2.2±0.3+
7.40	<u>Ø3.0</u>
0.50 3.20±0.5	\$0. *5
-2.54-	-4.75±0.5-
1 ~	_+ <mark>G</mark> 2

Notes:

Package dimensions

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25 mm (0.01") unless otherwise specified.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

Parameter	Symbol	Green	Unit mW	
Power Dissipation	Pd	80		
Forward Current	I _F	30	mA	
Peak Forward Current*1	I _{FP}	150	mA	
Reverse Voltage	V _R	5	V	
Operating Temperature	Topr	-40℃~80℃		
Storage Temperature	Tstg	-40℃~85℃		
Soldering Temperature	Tsol	255℃(for 5 seconds)		

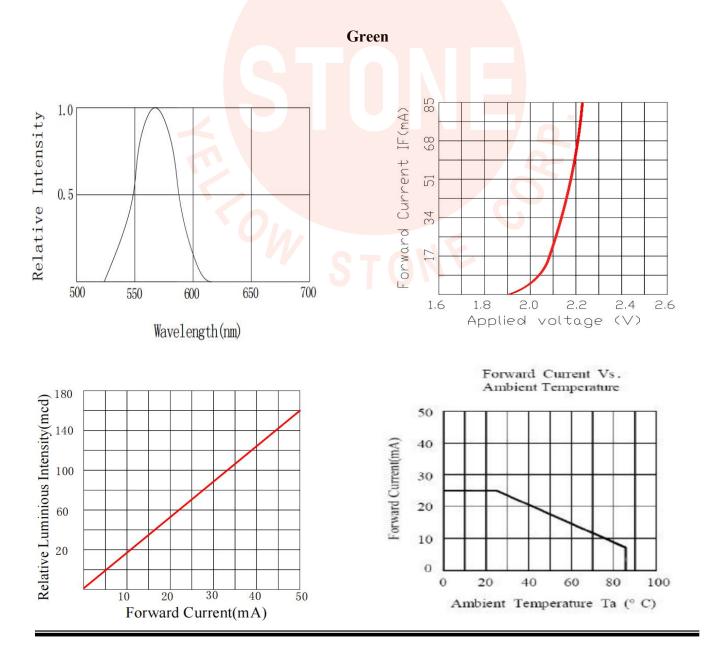
 $^{\star1}Condition$ for I_{FP} is pulse of 1/10 duty and 0.1msec width.



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Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
Forward Voltage	VF	I _F =20mA	Green	1.8		2.4	V
Luminous Intensity	Iv	I _F =20mA	Green	40		80	mcd
Reverse Current	I _R	V _R =1V	Green	-	-	10	μΑ
Peak Wave Length	λρ	I _F =20mA	Green	-	570	-	nm
Dominant Wave Length	λd	I _F =20mA	Green	565		575	nm
Spectral Line Half-width	Δλ	I⊧=20mA	Green	-	30	-	nm
Viewing Angle	2 θ _{1/2}	I _F =20mA	Green	-	50	-	deg

Typical Electro-Optical Characteristics Curves

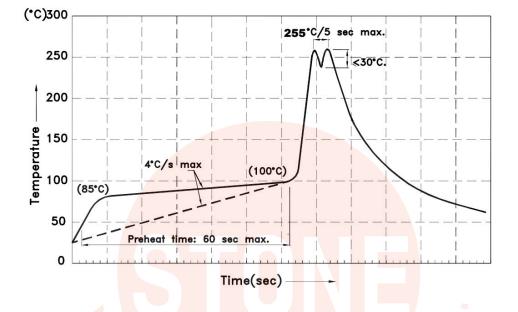


http://www.ystone.com.tw



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Dip Soldering



- 1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature,especially during soldering
- 2. DIP soldering and hand soldering should not be done more than one time.
- 3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
- 4. Avoid rapid cooling during temperature ramp-down process
- 5. Although the soldering condition is recommended above,

soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

- A: Max: 350°C Within 3 sec. One time only.
- B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350°C Within 2 sec. One time only 3.0(.118)

